

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application;

1. (Currently Amended) An electronics packaging system comprising:

a printer to print solder on lands of a printed wiring board;

a placing unit to place electronic parts on the lands of the printed wiring board having the solder printed thereon by the printer; and

a reflow unit to heat the printed wiring board on which the electronic parts have been placed by the placing unit and to solder the electronic parts to the printed wiring board₇₁ and

~~the printed wiring board being brought by a transfer mechanism, while being held to transfer the printed wiring board to the printer and through the printer to the placing unit and through the placing unit to the reflow unit, wherein the transfer mechanism includes horizontal upper and lower guide rails for capturing upper and lower edges of the printed wiring board and being attached to vertical support members, whereby the printed wiring board is maintained in a generally upright position, in order through the printer, the placing unit and the reflow unit.~~

2. (Previously Presented) The system according to claim 1, wherein:

land-position information is generated by a detecting

mechanism provided in the printer before the solder is printed by the printer on the lands of the printed wiring board; and

the placing unit places the electronic parts on the printed wiring board based on the land-position information.

3. - 17. (Cancelled)